



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32B106KLULNNF

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10 µF, 35V, ±10%, X7R, 1210

## A. Samsung Part Number

<u>CL</u> <u>32</u> <u>B</u> <u>106</u> <u>K</u> <u>L</u> <u>U</u> <u>L</u> <u>N</u> <u>N</u> <u>F</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	1210 (inch o	code) L	.: 3.2	± 0.3	mm	W:	$2.5 \pm 0.2$	mm
				8	Thickn	ess divis	ion	Low profile	
3	Dielectric	X7R			Inner e	electrode		Ni	
4	Capacitance	<b>10</b> μF			Termir	nation		Cu	
(5)	Capacitance	±10 %			Plating	J		Sn 100%	(Pb Free)
	tolerance			9	Produc	ct		Normal	
6	Rated Voltage	35 V		Special		Reserved for future use			
7	Thickness	$1.8 \pm 0.2$	mm	11)	Packag	ging		Embossed T	ype,13"reel(4,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms					
Tan δ (DF)	0.1 max.						
Insulation	More than 100Mohm⋅μF	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.	5% With rated voltage				
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0 hours				
	IR : More than 12.5MΩ·μF					
High Temperature	Capacitance change: within ±12.	With 150% of the rated voltage				
Resistance	Tan δ : 0.125 max	Max. operating temperature				
	IR : More than 25№ μF					
		1000+48/-0 hours				
Temperature	Capacitance change: within ±7.5	% 1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.